

# INTERNATIONAL STANDARD

# NORME INTERNATIONALE



**Semiconductor devices – Mechanical and climatic test methods –  
Part 10: Mechanical shock – Device and subassembly**

**Dispositifs à semiconducteurs – Méthodes d’essais mécaniques et climatiques –  
Partie 10: Chocs mécaniques – Dispositif et sous-ensemble**



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IEC Secretariat  
3, rue de Varembe  
CH-1211 Geneva 20  
Switzerland

Tel.: +41 22 919 02 11  
[info@iec.ch](mailto:info@iec.ch)  
[www.iec.ch](http://www.iec.ch)

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**SEMICONDUCTOR DEVICES –  
MECHANICAL AND CLIMATIC TEST METHODS –****Part 10: Mechanical shock – Device and subassembly**

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This edition cancels and replaces the first edition published in 2002. This edition includes the following significant technical changes with respect to the previous edition:

- a) covers both unattached components and components attached to printed wiring boards;
- b) tolerance limits modified for peak acceleration and pulse duration;
- c) mathematical formulae added for velocity change and equivalent drop height.

The text of this International Standard is based on the following documents:

Draft	Report on voting
47/2752/FDIS	47/2760/RVD

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

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